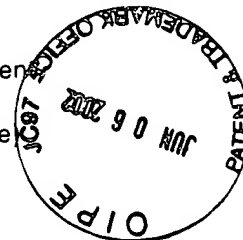


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ENCLOSURES:

- ☐ Application \_\_\_\_\_
- ☐ Specification \_\_\_\_\_ pages
- ☐ Claims \_\_\_\_\_ pages
- ☐ Abstract \_\_\_\_\_ page(s)
- ☐ Drawing Sheets no. \_\_\_\_\_ (F) \_\_\_\_\_ (INF) \_\_\_\_\_
- ☐ Transmittal Letter
- ☐ Check \$ \_\_\_\_\_ No: \_\_\_\_\_
- ☐ Declaration/Oath
- ☐ Assignment and Cover Sheet
- ☒ Information Disclosure Statement
- ☐ Response/Amendment
- ☐ Extension of Time (In Duplicate)
- ☐ Small Entity Status
- ☐ Copy of Priority Document
- ☒ Election



RE: APPLICATION

ATTY/SEC: MTM/bg

File no: 3EL 154

Applicant: Shunpei YAMAZAKI

S.N.: 09/479,262 Filing Date: January 5, 2000

Title: Semiconductor Device And  
Method of Manufacturing The  
Same

Due date: \_\_\_\_\_ Date Sent: 5-24-02

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